

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-113812



(43)Date of publication of application : 16.04.2002

(51)Int.Cl.

B32B 15/08
B32B 27/34
H05K 3/00
H05K 3/38
H05K 3/46

(21)Application number : 2001-037128

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(22)Date of filing : 14.02.2001

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(30)Priority

Priority number : 2000034853
2000235130

Priority date : 14.02.2000
03.08.2000

Priority country : JP

JP

(54) LAMINATE OF POLYIMIDE AND CONDUCTOR LAYER AND MULTILAYER INTERCONNECTION BOARD USING THE SAME AS WELL AS ITS MANUFACTURING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a laminate having excellent adhesive properties between a conductor and a polyimide film without using physical surface roughing and an adhesive metal layer.

SOLUTION: The laminate of a polyimide obtained by directly forming at least one conductor layer on the surface of a thermoplastic polyimide and a conductor layer is pressurized and heat treated, heat fusion bonded to strengthen an adhesive strength of the polyimide and the conductor layer.

LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right]

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